

# ABSTRACT

A method for manufacturing a printed wiring board, including the steps of: forming a thermosetting resin layer so as to fill the spaces between circuit patterns formed on the printed wiring board; heating and curing the resin layer in a reduced pressure chamber in which the pressure is reduced while a smoothing plate is pressed against the resin layer; and then polishing the cured resin layer covering the circuit patterns, thereby exposing the circuit patterns. The step of heating and curing the resin layer in the reduced pressure chamber comprises the following successively performed steps: step 1: maintaining the resin layer at a non-curable temperature to prevent the resin layer from curing, in a state where the resin layer is pressed via the smoothing plate in the reduced pressure chamber; step 2: heating the resin layer in the pressed state to a curing temperature at which the resin layer is cured; step 3: introducing outside air into the reduced pressure chamber with the pressed state and the curing temperature maintained; step 4: reducing the pressure applied to the smoothing plate with the curing temperature maintained; and step 5: cooling the resin layer.